Very Low Forward Voltage Trench-based Schottky Rectifier

Exceptionally Low $V_F = 0.36 \text{ V}$ at $I_F = 5 \text{ A}$

Features

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- Halide Free Devices Available
- These are Pb-Free Packages

Typical Applications

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC-DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Maximum for 10 sec

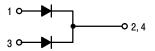


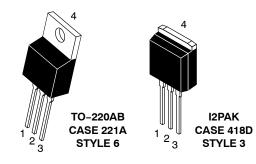
ON Semiconductor®

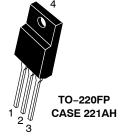
www.onsemi.com

VERY LOW FORWARD VOLT-AGE, LOW LEAKAGE SCHOT-TKY BARRIER RECTIFIERS 60 AMPERES, 100 VOLTS

PIN CONNECTIONS









ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
Average Rectified Forward Current at Rated V_R NTST60100CT, NTSB60100CT–1 and NTSB60100CT (Rated V_R , T_C = 115°C) per Device (Rated V_R , T_C = 125°C) per Diode NTSJ60100CT (Rated V_R , T_C = 80°C) per Device (Rated V_R , T_C = 75°C) per Diode	I _{F(AV)}	60 30 30 30	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz) NTST60100CT, NTSB60100CT–1 and NTSB60100CT (Rated V_R , T_C = 105°C) per Device (Rated V_R , T_C = 120°C) per Diode NTSJ60100CT (Rated V_R , T_C = 65°C) per Device (Rated V_R , T_C = 55°C) per Diode	I _{FRM}	120 60 30 30	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	250	Α
Operating Junction Temperature	TJ	-40 to +150	°C
Storage Temperature	T _{stg}	-40 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Rating	Symbol	NTST60100CT, NTSB60100CT-1, NTSB60100CT	NTSJ60100CT	Unit
Maximum Thermal Resistance Junction-to-Case Per I Per D	R _{θJC} Diode evice	1.10 0.67	3.60 3.17	°C/W

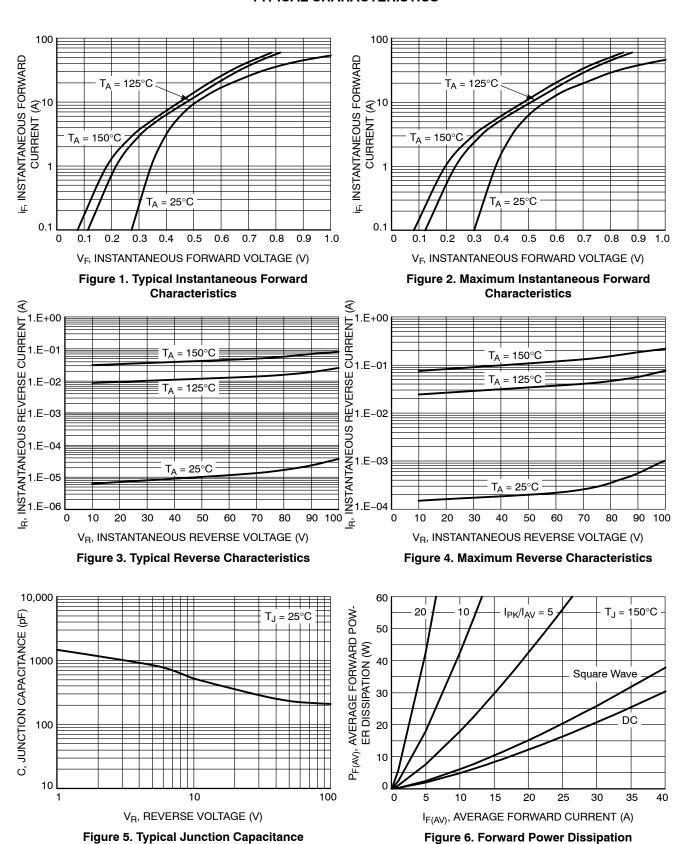
ELECTRICAL CHARACTERISTICS (Per Leg unless otherwise noted)

Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1)	٧ _F			V
$(I_F = 5 \text{ A}, T_J = 25^{\circ}\text{C})$		0.45	_	
$(I_F = 10 \text{ A}, T_J = 25^{\circ}\text{C})$		0.52	_	
$(I_F = 15 \text{ A}, T_J = 25^{\circ}\text{C})$		0.58	0.63	
$(I_F = 20 \text{ A}, T_J = 25^{\circ}\text{C})$		0.63	_	
$(I_F = 30 \text{ A}, T_J = 25^{\circ}\text{C})$		0.73	0.84	
$(I_F = 5 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 10 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 15 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 20 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 30 \text{ A}, T_J = 125^{\circ}\text{C})$		0.36 0.45 0.53 0.58 0.66	- 0.58 - 0.70	
Maximum Instantaneous Reverse Current (Note 1)	I _R			
$(V_R = 80 \text{ V}, T_J = 25^{\circ}\text{C})$		20	500	μΑ
$(V_R = 80 \text{ V}, T_J = 125^{\circ}\text{C})$		15	20	mA
(Rated dc Voltage, T _J = 25°C) (Rated dc Voltage, T _J = 125°C)		40 30	1000 85	μA mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{1.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

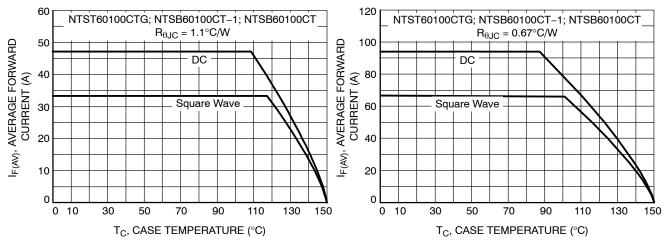


Figure 7. Current Derating per Diode

Figure 8. Current Derating per Device

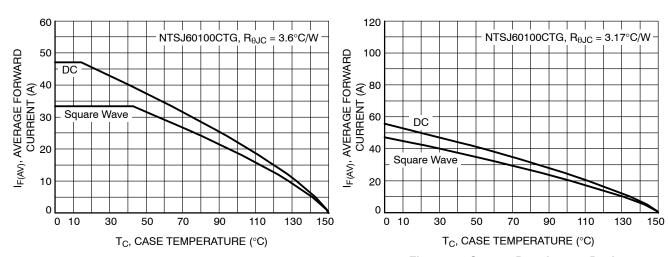


Figure 9. Current Derating per Diode

Figure 10. Current Derating per Device

TYPICAL CHARACTERISTICS

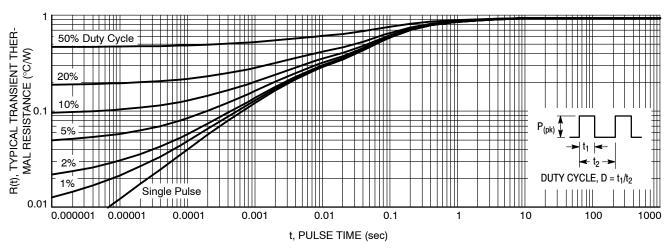


Figure 11. NTST60100CT, NTSB60100CT-1G and NTSB60100CT Typical Transient Thermal Response

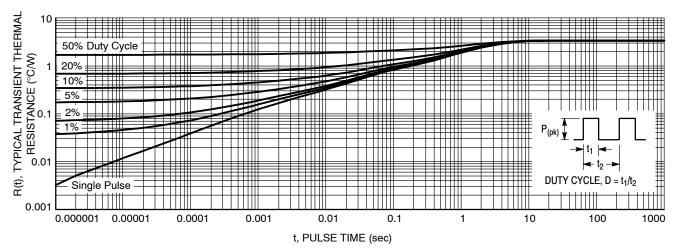
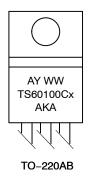


Figure 12. NTSJ60100CTG Typical Transient Thermal Response

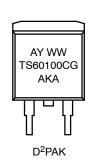
ORDERING INFORMATION

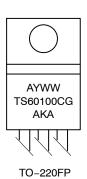
Device	Package	Shipping
NTST60100CTG	TO-220AB (Pb-Free)	50 Units / Rail
NTSB60100CT-1G	I ² PAK (Pb-Free)	50 Units / Rail
NTSB60100CTG	D ² PAK (Pb-Free)	50 Units / Rail
NTSB60100CTT4G	D ² PAK (Pb-Free)	800 / Tape & Reel
NTSJ60100CTG	TO-220FP (Halide-Free, Pb-Free)	50 Units / Rail

MARKING DIAGRAMS







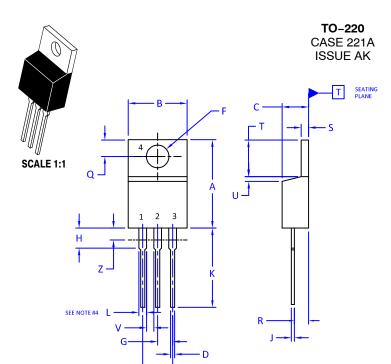


A = Assembly Location

Y = Year WW = Work Week AKA = Polarity Designator

x = G or H

G = Pb-Free Package H = Halide-Free Package



DATE 13 JAN 2022

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

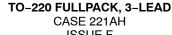
4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMI	ETERS
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

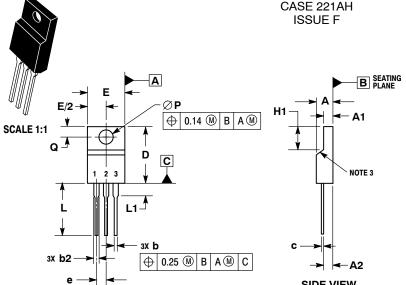
STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11:		STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

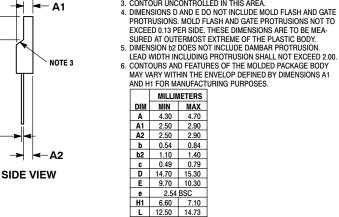
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DATE 30 SEP 2014

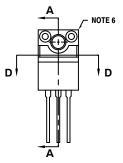


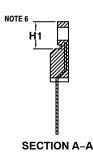


NOTES:



FRONT VIEW





ALTERNATE CONSTRUCTION

GENERIC MARKING DIAGRAM*

4.70

2.90

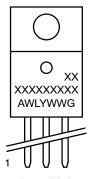
1.40

0.79

7.10

2.80 3.00 3.40

 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR UNCONTROLLED IN THIS AREA.



= Assembly Location

WL = Wafer Lot

= Year

WW = Work Week

G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1:		STYLE 2:	
PIN 1.	MAIN TERMINAL 1	PIN 1.	CATHODE
2.	MAIN TERMINAL 2	2.	ANODE
3.	GATE	3.	GATE

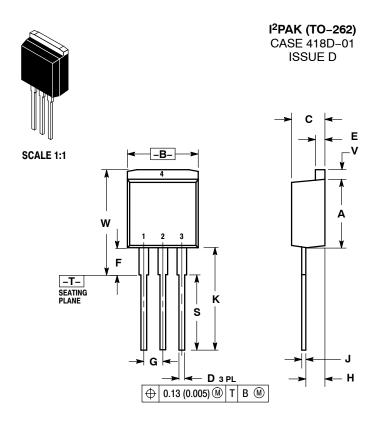
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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS





DATE 16 OCT 2007

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.335	0.380	8.51	9.65
В	0.380	0.406	9.65	10.31
С	0.160	0.185	4.06	4.70
D	0.026	0.035	0.66	0.89
Ε	0.045	0.055	1.14	1.40
F	0.122	REF	3.10 REF	
G	0.100	BSC	2.54	BSC
Н	0.094	0.110	2.39	2.79
J	0.013	0.025	0.33	0.64
K	0.500	0.562	12.70	14.27
S	0.390 REF		9.90	REF
٧	0.045	0.070	1.14	1.78
W	0.522	0.551	13.25	14.00

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:
PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. GATE
2. COLLECTOR	2. DRAIN	2. CATHODE	2. COLLECTOR
3. EMITTER	SOURCE	3. ANODE	3. EMITTER
COLLECTOR	4. DRAIN	4. CATHODE	COLLECTOR

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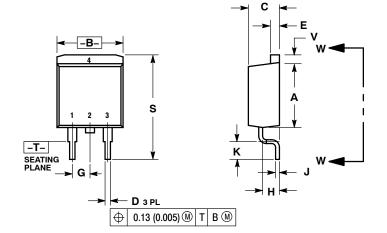
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D²PAK 3 CASE 418B-04 **ISSUE L**

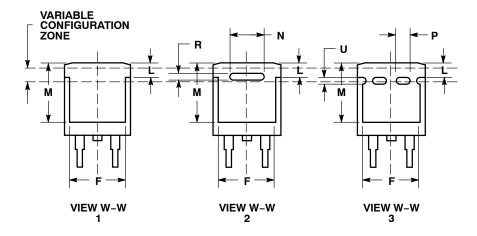
DATE 17 FEB 2015

SCALE 1:1



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
7	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
М	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
Р	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40



STYLE 1: PIN 1. BASE 2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 2: PIN 1. GATE 2. DRAIN

3. SOURCE 4. DRAIN

STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

STYLE 4:

PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE

4. CATHODE

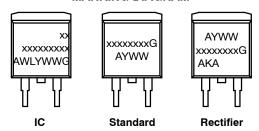
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DATE 17 FEB 2015

GENERIC MARKING DIAGRAM*



xx = Specific Device Code A = Assembly Location

 WL
 = Wafer Lot

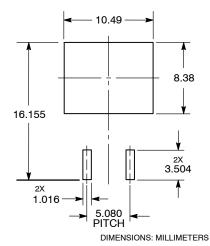
 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

 AKA
 = Polarity Indicator

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

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